


☒ For dense holes area or hole size $<0.6\text{mm}$, LE aluminum cover layer is recommended.

☒ For hole siz



☒ Suggest baking finished boards at 140 °C / 4~6h before packaging to prevent moisture effect

☒ Package material is recommended using aluminum foil (4Do26 Tm/GS13 gs.9ET EM /P <</MID 14/Lang 3en-35F3 9.